

# **SLOVENSKI STANDARD**

## **SIST EN 62137-4:2015**

**01-september-2015**

**Nadomešča:**  
**SIST EN 62137:2005**

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**Tehnologija elektronskega sestavljanja - 4. del: Metode za preskušanje  
vzdržljivosti kositrnih spojev elementov za površinsko montažo z okrovi z  
matričnimi priključki v ravnini**

Electronics assembly technology - Part 4: Endurance test methods for solder joint of area  
array type package surface mount devices

**iTeh STANDARD PREVIEW**  
Montageverfahren für elektronische Baugruppen - Teil 4: Oberflächenmontierbare  
Bauteilgehäuse mit Flächenmatrix - (Lebens)dauerprüfungen für Lötverbindungen

**SIST EN 62137-4:2015**  
Technique d'assemblage des composants électroniques - Partie 4: Méthodes d'essais  
d'endurance des joints brasés des composants pour montage en surface à boîtiers de  
type matriciel

**Ta slovenski standard je istoveten z: EN 62137-4:2014**

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**ICS:**

31.190

Sestavljeni elektronski  
elementi

Electronic component  
assemblies

**SIST EN 62137-4:2015**

**en**

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN 62137-4**

December 2014

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English Version

Electronics assembly technology -  
Part 4: Endurance test methods for solder joint of area array type  
package surface mount devices  
(IEC 62137-4:2014)

Technique d'assemblage des composants électroniques -  
Partie 4: Méthodes d'essais d'endurance des joints brasés  
des composants pour montage en surface à boîtiers de  
type matriciel  
(CEI 62137-4:2014)

Montageverfahren für elektronische Baugruppen -  
Teil 4: Oberflächenmontierbare Bauteilgehäuse mit  
Flächenmatrix - (Lebens-)Dauerprüfungen für  
Lötverbindungen  
(IEC 62137-4:2014)

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Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels**

## Foreword

The text of document 91/1188/FDIS, future edition 1 of IEC 62137-4, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62137-4:2014.

The following dates are fixed:

- latest date by which the document has to be (dop) 2015-08-13  
implemented at national level by  
publication of an identical national  
standard or by endorsement
- latest date by which the national (dow) 2017-11-13  
standards conflicting with the  
document have to be withdrawn

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## Endorsement notice

The text of the International Standard IEC 62137-4:2014 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-1:1988+A1:1992	NOTE	Harmonized as EN 60068-1:1994 (not modified).
IEC 60068-2-2	NOTE	Harmonized as EN 60068-2-2.
IEC 60068-2-6	NOTE	Harmonized as EN 60068-2-6.
IEC 60068-2-21:2006	NOTE	Harmonized as EN 60068-2-21:2006 (not modified).
IEC 60068-2-27	NOTE	Harmonized as EN 60068-2-27.
IEC 60068-2-44:1995	NOTE	Harmonized as EN 60068-2-44:1995 (not modified).
IEC 60068-2-58:2004	NOTE	Harmonized as EN 60068-2-58:2004 (not modified).
IEC 60068-2-78:2001	NOTE	Harmonized as EN 60068-2-78:2001 <sup>1)</sup> (not modified).
IEC 60749-1:2002	NOTE	Harmonized as EN 60749-1:2003 (not modified).
IEC 60749-20:2008	NOTE	Harmonized as EN 60749-20:2009 (not modified).
IEC 60749-20-1:2009	NOTE	Harmonized as EN 60749-20-1:2009 (not modified).
IEC 61188-5-8	NOTE	Harmonized as EN 61188-5-8.
IEC 61189-3:2007	NOTE	Harmonized as EN 61189-3:2008 (not modified).
IEC 61189-5	NOTE	Harmonized as EN 61189-5.
IEC 61190-1-1	NOTE	Harmonized as EN 61190-1-1.
IEC 61190-1-2	NOTE	Harmonized as EN 61190-1-2.
IEC 61760-1:2006	NOTE	Harmonized as EN 61760-1:2006 (not modified).
IEC 62137-1-3	NOTE	Harmonized as EN 62137-1-3.
IEC 62137-1-4:2009	NOTE	Harmonized as EN 62137-1-4:2009 (not modified).

<sup>1)</sup> Superseded by EN 60068-2-78:2013 (IEC 60068-2-78:2012): DOW = 2015-12-03.

## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu)

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60191-6-2	-	Mechanical standardization of semiconductor devices - Part 6-2: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for 1,50 mm, 1,27 mm and 1,00 mm pitch ball and column terminal packages	EN 60191-6-2	-
IEC 60191-6-5	-	Mechanical standardization of semiconductor devices - Part 6-5: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine-pitch ball grid array (FBGA)	EN 60191-6-5	-
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61190-1-3	-	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non- fluxed solid solders for electronic soldering applications	EN 61190-1-3	-
IEC 61249-2-7	-	Materials for printed boards and other interconnecting structures - Part 2-7: Reinforced base materials, clad and unclad - Epoxide woven E-glass laminated sheet of defined flammability (vertical burning test), copper-clad	EN 61249-2-7	-
IEC 61249-2-8	-	Materials for printed boards and other interconnecting structures - Part 2-8: Reinforced base materials, clad and unclad - Modified brominated epoxide woven fibreglass reinforced laminated sheets of defined flammability (vertical burning test), copper-clad	EN 61249-2-8	-

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62137-3	2011	Electronics assembly technology - Part 3: Selection guidance of environmental and endurance test methods for solder joints	EN 62137-3	2012

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[SIST EN 62137-4:2015](https://standards.iteh.ai/catalog/standards/sist/c1b3c320-574a-47bf-b759-9e318ec52d92/sist-en-62137-4-2015)

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Edition 1.0 2014-10

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Electronics assembly technology –  
Part 4: Endurance test methods for solder joint of area array type package  
surface mount devices**

**Technique d'assemblage des composants électroniques –  
Partie 4: Méthodes d'essais d'endurance des joints brasés des composants  
pour montage en surface à boîtiers de type matriciel**

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## CONTENTS

FOREWORD .....	6
1 Scope .....	8
2 Normative references .....	8
3 Terms definitions and abbreviations .....	9
3.1 Terms and definitions .....	9
3.2 Abbreviations .....	9
4 General .....	9
5 Test apparatus and materials .....	10
5.1 Specimen .....	10
5.2 Reflow soldering equipment .....	10
5.3 Temperature cycling chamber .....	10
5.4 Electrical resistance recorder .....	10
5.5 Test substrate .....	10
5.6 Solder paste .....	11
6 Specimen preparation .....	11
7 Temperature cycling test .....	13
7.1 Pre-conditioning .....	13
7.2 Initial measurement .....	13
7.3 Test procedure .....	13
7.4 End of test criteria .....	15
7.5 Recovery .....	15
7.6 Final measurement .....	15
8 Temperature cycling life .....	15
9 Items to be specified in the relevant product specification .....	15
Annex A (informative) Acceleration of the temperature cycling test for solder joints .....	17
A.1 General .....	17
A.2 Acceleration of the temperature cycling test for an Sn-Pb solder joint .....	17
A.3 Temperature cycling life prediction method for an Sn-Ag-Cu solder joint .....	18
A.4 Factor that affects the temperature cycling life of the solder joint .....	22
Annex B (informative) Electrical continuity test for solder joints of the package .....	23
B.1 General .....	23
B.2 Package and daisy chain circuit .....	23
B.3 Mounting condition and materials .....	23
B.4 Test method .....	23
B.5 Temperature cycling test using the continuous electric resistance monitoring system .....	23
Annex C (informative) Reflow solderability test method for package and test substrate land .....	25
C.1 General .....	25
C.2 Test equipment .....	25
C.2.1 Test substrate .....	25
C.2.2 Pre-conditioning oven .....	25
C.2.3 Solder paste .....	25
C.2.4 Metal mask for screen printing .....	25
C.2.5 Screen printing equipment .....	25



C.2.6	Package mounting equipment.....	25
C.2.7	Reflow soldering equipment.....	25
C.2.8	X-ray inspection equipment .....	26
C.3	Standard mounting process .....	26
C.3.1	Initial measurement .....	26
C.3.2	Pre-conditioning .....	26
C.3.3	Package mounting on test substrate .....	26
C.3.4	Recovery .....	27
C.3.5	Final measurement .....	27
C.4	Examples of faulty soldering of area array type packages .....	27
C.4.1	Repelled solder by contamination on the ball surface of the BGA package.....	27
C.4.2	Defective solder ball wetting caused by a crack in the package .....	27
C.5	Items to be given in the product specification.....	28
Annex D (informative)	Test substrate design guideline.....	29
D.1	General.....	29
D.2	Design standard.....	29
D.2.1	General .....	29
D.2.2	Classification of substrate specifications.....	29
D.2.3	Material of the test substrate .....	31
D.2.4	Configuration of layers of the test substrate.....	31
D.2.5	Land shape of test substrate.....	31
D.2.6	Land dimensions of the test substrate.....	31
D.3	Items to be given in the product specification.....	32
Annex E (informative)	Heat resistance to reflow soldering for test substrate .....	33
E.1	General.....	33
E.2	Test apparatus.....	33
E.2.1	Pre-conditioning oven .....	33
E.2.2	Reflow soldering equipment.....	33
E.3	Test procedure.....	33
E.3.1	General .....	33
E.3.2	Pre-conditioning .....	33
E.3.3	Initial measurement .....	33
E.3.4	Moistening process (1) .....	34
E.3.5	Reflow heating (1) .....	34
E.3.6	Moistening process (2) .....	34
E.3.7	Reflow heating process (2) .....	34
E.3.8	Final measurement .....	34
E.4	Items to be given in the product specification.....	34
Annex F (informative)	Pull strength measurement method for the test substrate land.....	35
F.1	General.....	35
F.2	Test apparatus and materials.....	35
F.2.1	Pull strength measuring equipment.....	35
F.2.2	Reflow soldering equipment.....	35
F.2.3	Test substrate.....	35
F.2.4	Solder ball .....	35
F.2.5	Solder paste .....	35
F.2.6	Flux .....	35
F.3	Measurement procedure .....	36

F.3.1	Pre-conditioning .....	36
F.3.2	Solder paste printing.....	36
F.3.3	Solder ball placement .....	36
F.3.4	Reflow heating process .....	36
F.3.5	Pull strength measurement .....	36
F.3.6	Final measurement .....	37
F.4	Items to be given in the product specification.....	37
Annex G (informative)	Standard mounting process for the packages.....	38
G.1	General.....	38
G.2	Test apparatus and materials.....	38
G.2.1	Test substrate.....	38
G.2.2	Solder paste .....	38
G.2.3	Metal mask for screen printing .....	38
G.2.4	Screen printing equipment .....	38
G.2.5	Package mounting equipment.....	38
G.2.6	Reflow soldering equipment.....	38
G.3	Standard mounting process .....	39
G.3.1	Initial measurement .....	39
G.3.2	Solder paste printing.....	39
G.3.3	Package mounting .....	39
G.3.4	Reflow heating process .....	39
G.3.5	Recovery .....	40
G.3.6	Final measurement .....	40
G.4	Items to be given in the product specification .....	40
Annex H (informative)	Mechanical stresses to the packages.....	41
H.1	General.....	41
H.2	Mechanical stresses .....	41
Bibliography	.....	42
Figure 1	– Region for evaluation of the endurance test .....	10
Figure 2	– Typical reflow soldering profile for Sn63Pb37 solder alloy .....	12
Figure 3	– Typical reflow soldering profile for Sn96,5Ag3Cu,5 solder alloy.....	13
Figure 4	– Test conditions of temperature cycling test.....	14
Figure A.1	– FBGA package device and FEA model for calculation of acceleration factors $AF$ .....	20
Figure A.2	– Example of acceleration factors $AF$ with an FBGA package device using Sn96,5Ag3Cu,5 solder alloy.....	21
Figure A.3	– Fatigue characteristics of Sn96,5Ag3Cu,5 an alloy micro solder joint ( $N_f = 20$ % load drop from initial load) .....	22
Figure B.1	– Example of a test circuit for the electrical continuity test of a solder joint .....	23
Figure B.2	– Measurement example of continuously monitored resistance in the temperature cycling test.....	24
Figure C.1	– Temperature measurement of specimen using thermocouples .....	26
Figure C.2	– Repelled solder caused by contamination on the solder ball surface .....	27
Figure C.3	– Defective soldering as a result of a solder ball drop .....	28
Figure D.1	– Standard land shapes of the test substrate .....	31
Figure F.1	– Measuring methods for pull strength .....	36

Figure G.1 – Example of printed conditions of solder paste .....	39
Figure G.2 – Temperature measurement of the specimen using thermocouples .....	40
Table 1 – Test conditions of temperature cycling test.....	14
Table A.1 – Example of test results of the acceleration factor (Sn63Pb37 solder alloy) .....	18
Table A.2 – Example test results of the acceleration factor (Sn96,5Ag3Cu,5 solder alloy) .....	20
Table A.3 – Material constant and inelastic strain range calculated by FEA for FBGA package devices as shown in Figure A.1 (Sn96,5Ag3Cu,5 solder alloy) .....	21
Table D.1 – Types classification of the test substrate.....	30
Table D.2 – Standard layers' configuration of test substrates .....	31
Table G.1 – Stencil design standard for packages .....	38
Table H.1 – Mechanical stresses to mounted area array type packages.....	41

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SIST EN 62137-4:2015

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRONICS ASSEMBLY TECHNOLOGY –****Part 4: Endurance test methods for solder joint  
of area array type package surface mount devices****FOREWORD**

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International Standard IEC 62137-4 has been prepared by IEC technical committee 91: Electronics assembly technology.

IEC 62137-4 (first edition) cancels and replaces IEC 62137:2004. This edition constitutes a technical revision.

IEC 62137-4 includes the following significant technical changes with respect to IEC 62137:2004:

- test conditions for use of lead-free solder are included;
- test conditions for lead-free solders are added;
- accelerations of the temperature cycling test for solder joints are added.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1188/FDIS	91/1205/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62137 series, published under the general title *Electronics assembly technology* can be found in the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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